

Page 1:

Please replace the fourth paragraph as follows:

BACKGROUND OF THE INVENTION

X2
The state of the art includes the so-called stand alone measuring machines, which are installed at central points of the plant. Due to the high cost of these systems and the relatively high space requirement, only a few of these systems can be installed. One drawback is also the additional paths, the additional loading and unloading steps of the wafers from the transport boxes and back again. Moreover, much time is lost between the detection of a defect and the reaction, a state that can result in enormous losses as the process speed increases and the value of the individual wafers increases dramatically.

Page 3:

Please replace the third full paragraph as follows:

SUMMARY OF THE INVENTION

X3
The object of the invention is to provide a device to carry out the measurements in the vacuum. Said device ought not to exhibit either the drawbacks of the stand alone devices or the *in situ* measuring devices, but rather permit a process oriented measurement under optimal measurement conditions.

Page 11:

Please replace third full paragraph as follows:

BRIEF DESCRIPTION OF THE SEVERAL VIEWS OF THE DRAWINGS

X4
The invention shall be explained in detail with reference to the example of an ellipsometric measurement of wafer surfaces.